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*RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCESSING
(GROUP 2811)

*#16/Formal
Drawing
1/30/03
Adm H*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Takuji MATSUMOTO ET AL. : GROUP ART UNIT: 2811

SERIAL NO: 09/729,816

FILED: DECEMBER 6, 2000 : EXAMINER: OWENS, D.

FOR: SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING
THE SAME

LETTER TO THE OFFICIAL DRAFTSMAN

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Any corrections required by the Chief Draftsman or drawings amendments approved by the Examiner have been incorporated into the copies of the Formal Drawings submitted herewith. It is requested that the enclosed 14 sheets of Formal Drawings be entered to replace the drawings previously filed in this application.

Respectfully submitted,

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Gregory J. Maier

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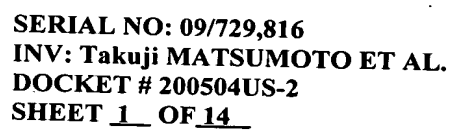
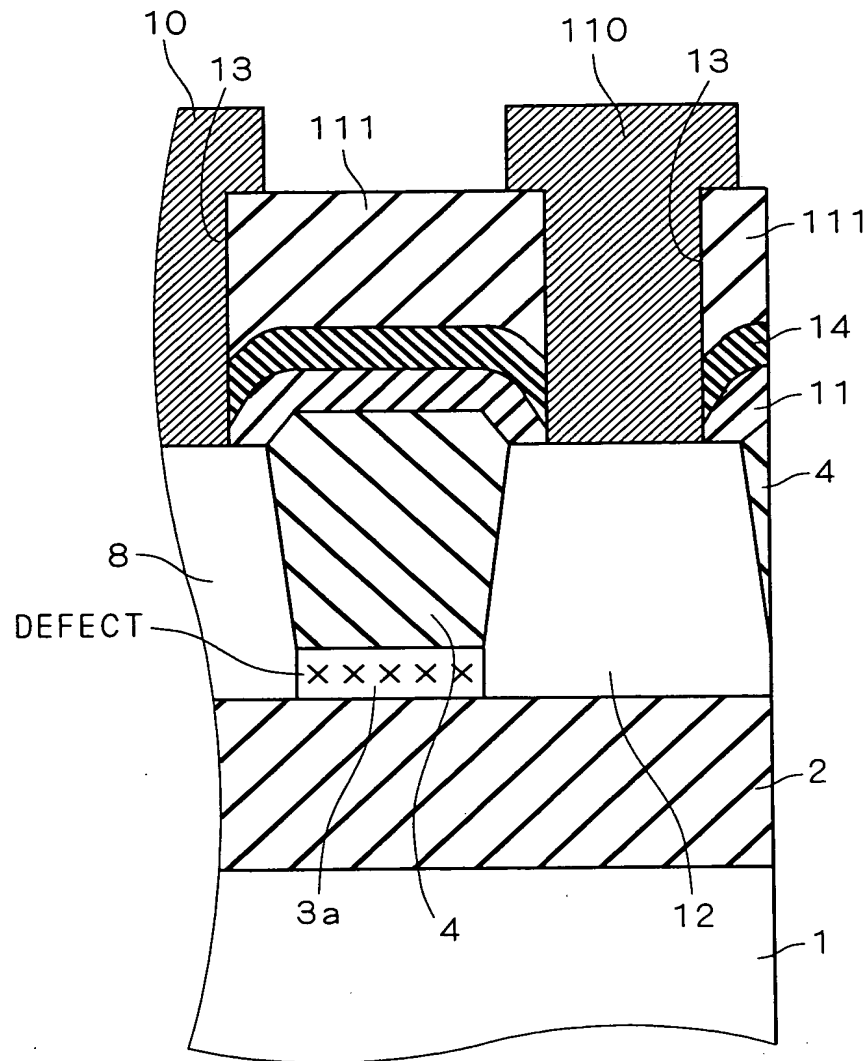
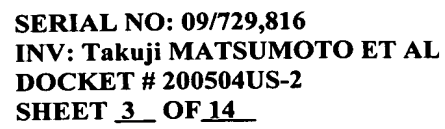




FIG. 3





A detailed cross-sectional diagram of a semiconductor device. The base layer is labeled 1. Above it is a layer with diagonal hatching, labeled 2. A thin layer labeled 3a sits on top of layer 2. On top of 3a are several trapezoidal structures labeled 4. Between these structures are recessed areas labeled 5. To the left of the first structure 4 is a vertical feature labeled 9. Further up, there's another layer with diagonal hatching labeled 6. Above that is a layer with horizontal hatching labeled 7. A series of rectangular blocks labeled 10 are positioned above the horizontal-hatched layer. Between these blocks are vertical features labeled 11. A layer with diagonal hatching labeled 12 covers the top of the blocks 10. Above this is a layer with horizontal hatching labeled 13. At the very top, there are more rectangular blocks labeled 14. Various other labels like 110, 111, 81, 82, 71, 72, 13, 14, 3, 8, 12, 3a, 4, 5, 9, 10, 6, 7, 11, 111, 14, 11, 4, 3a, 2, 1 are used to identify specific components and interfaces throughout the stack.



FIG. 6

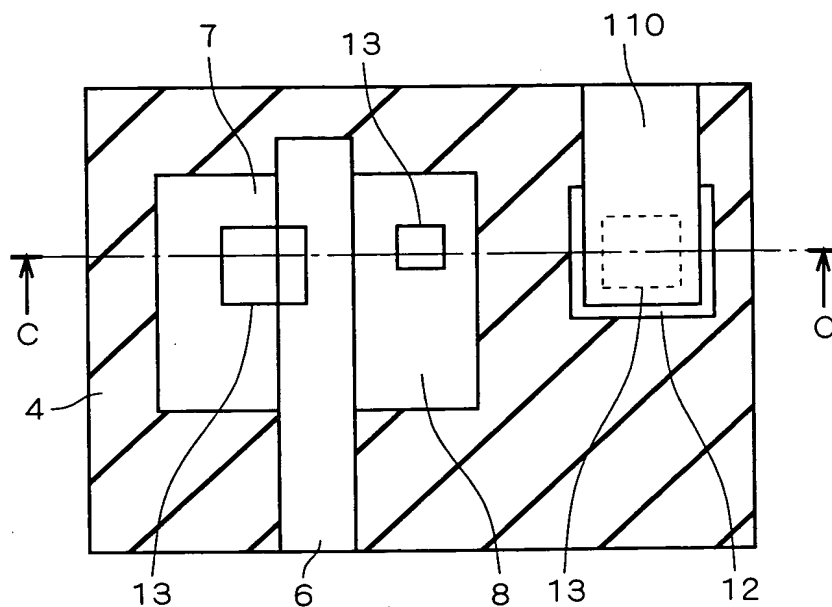


FIG. 7

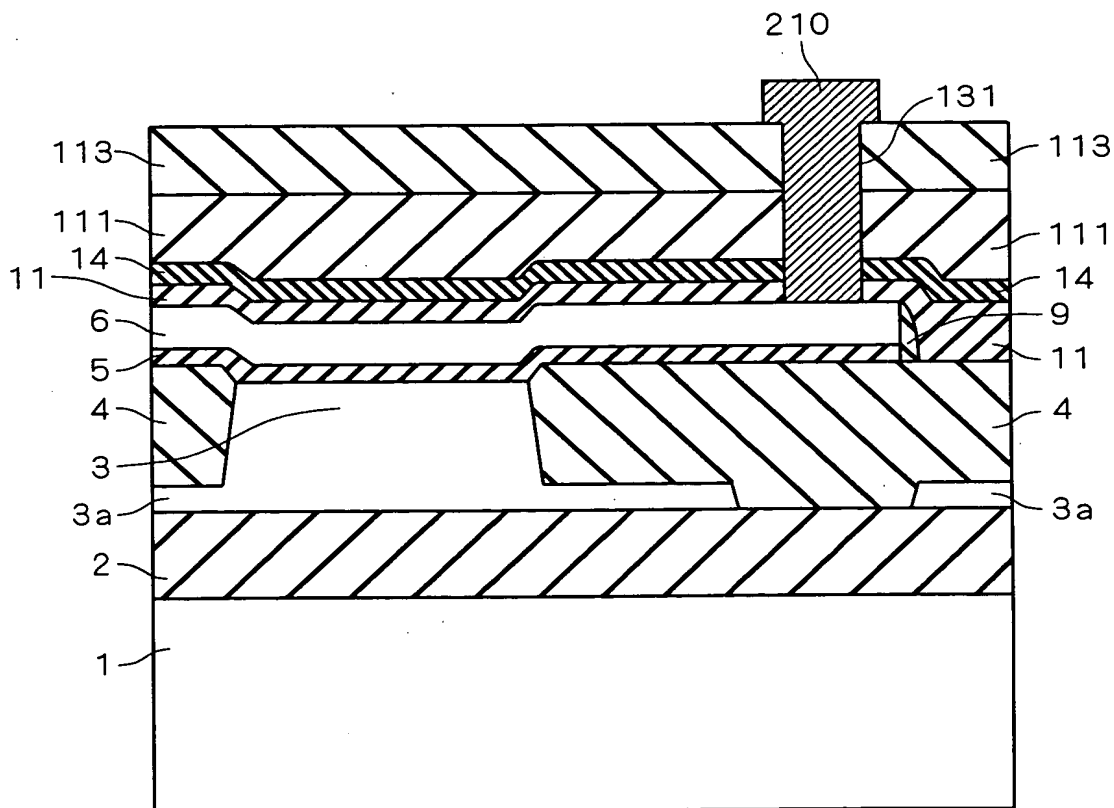




FIG. 8

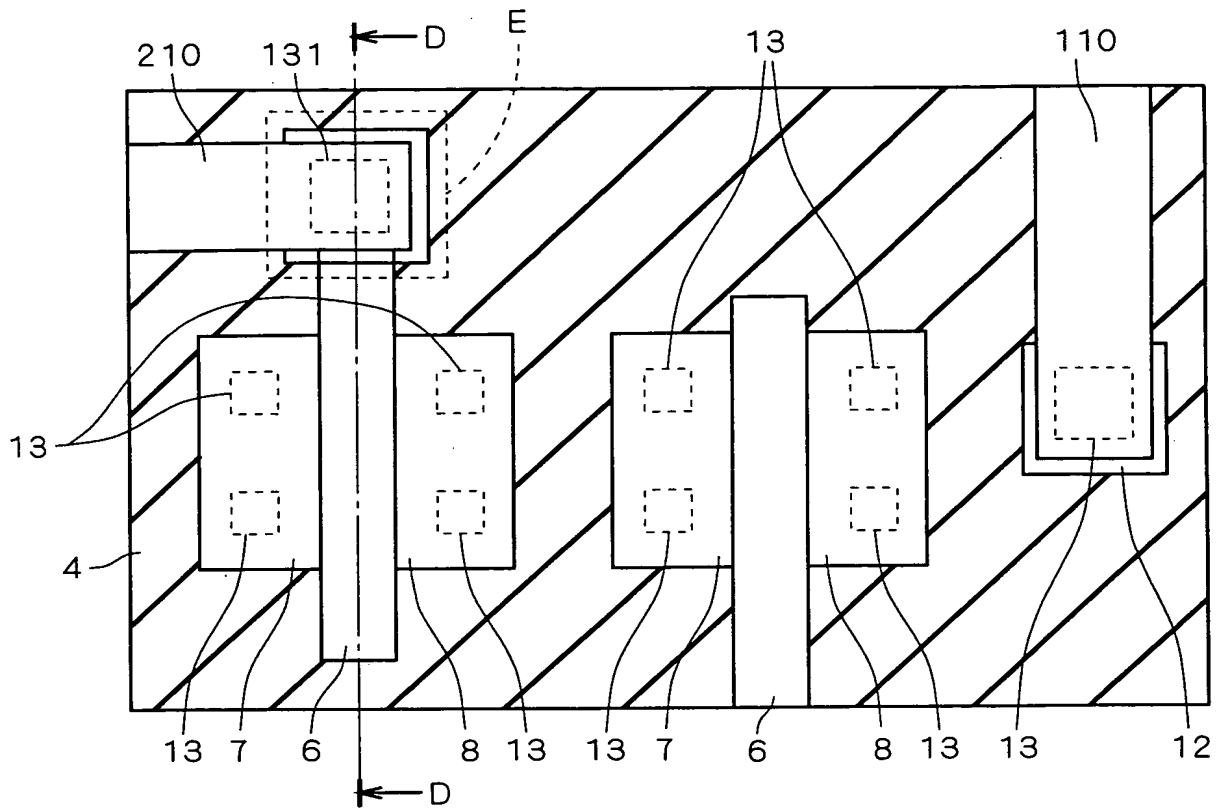


FIG. 9

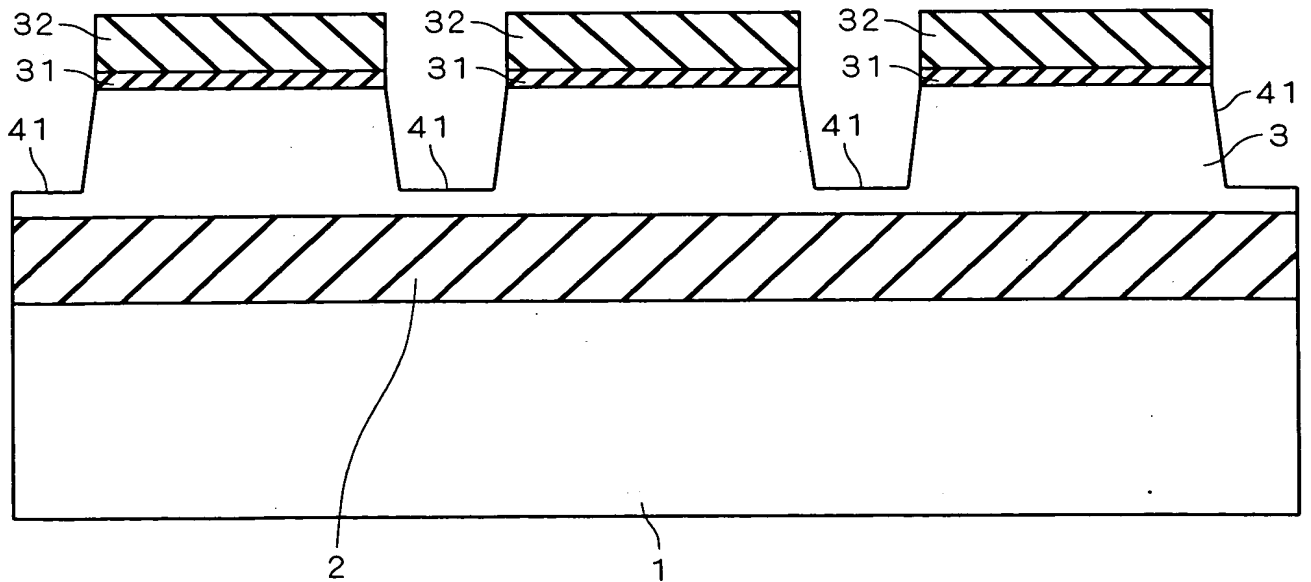




FIG. 10

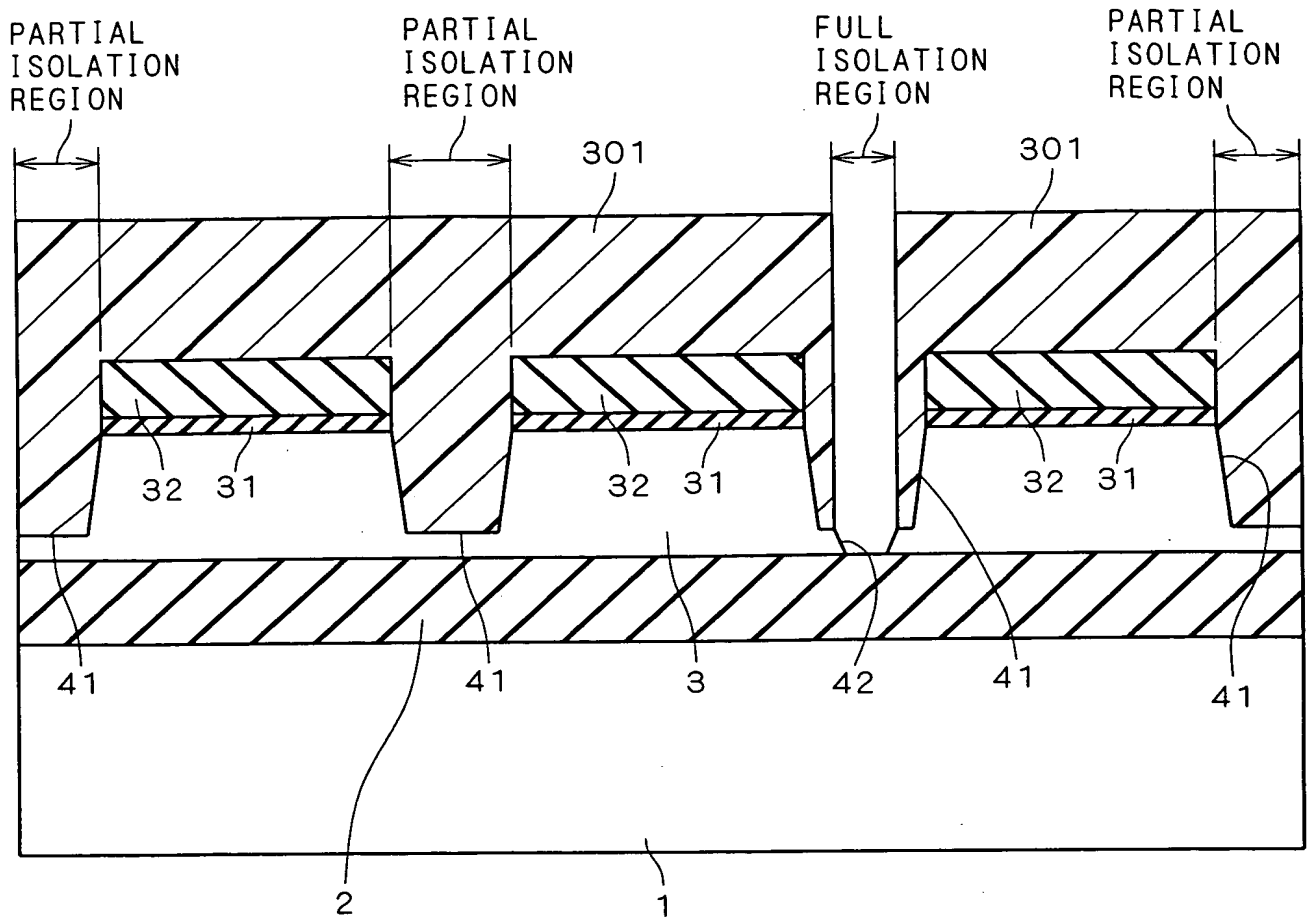


FIG. 11

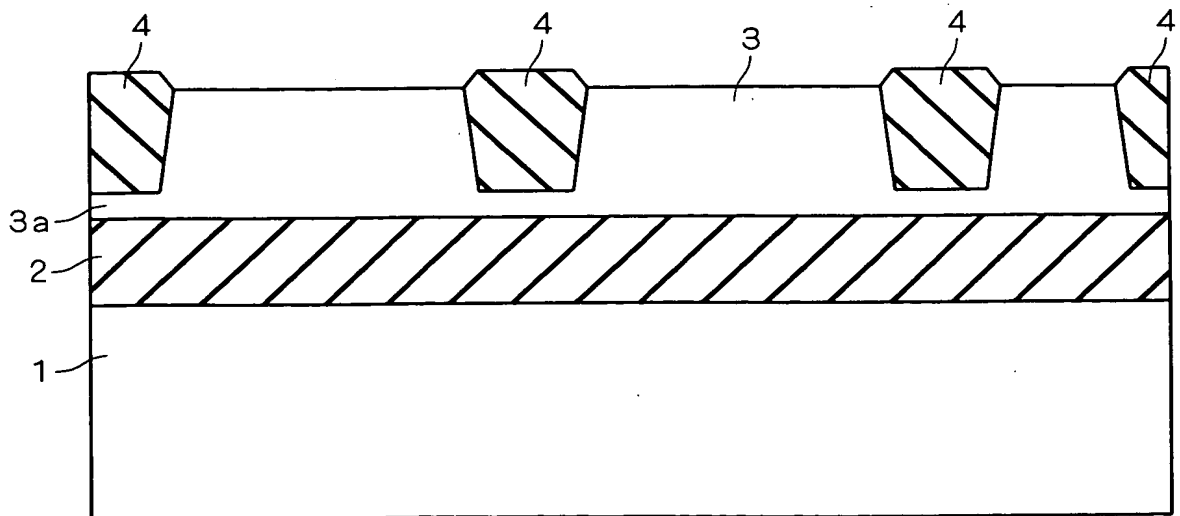




FIG. 12

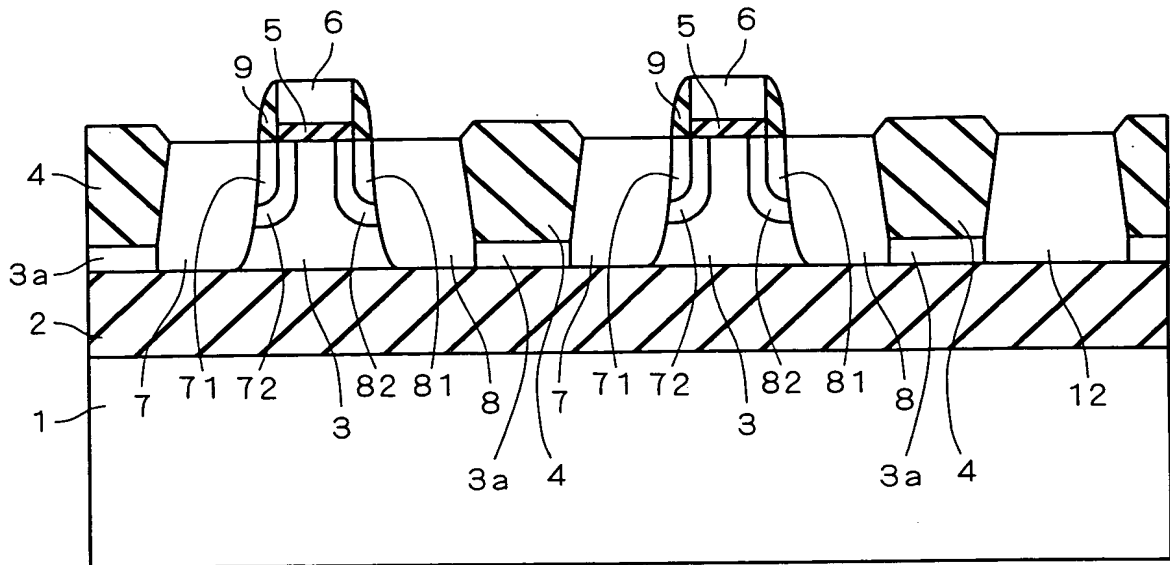
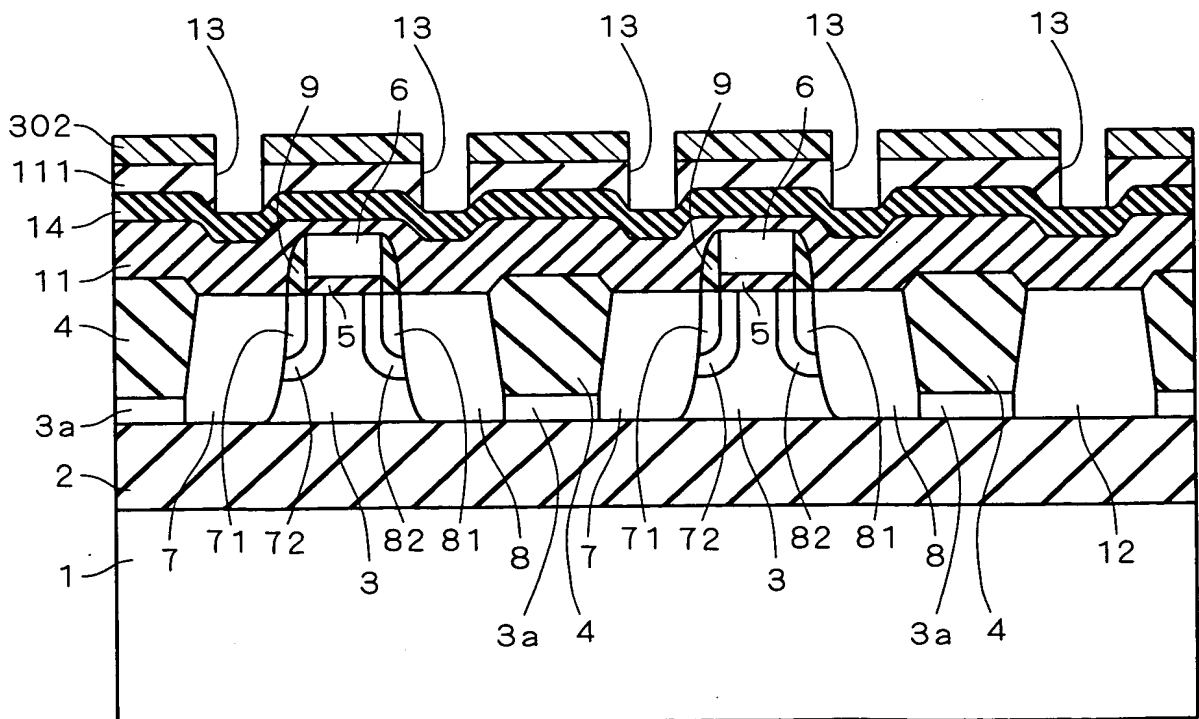


FIG. 13



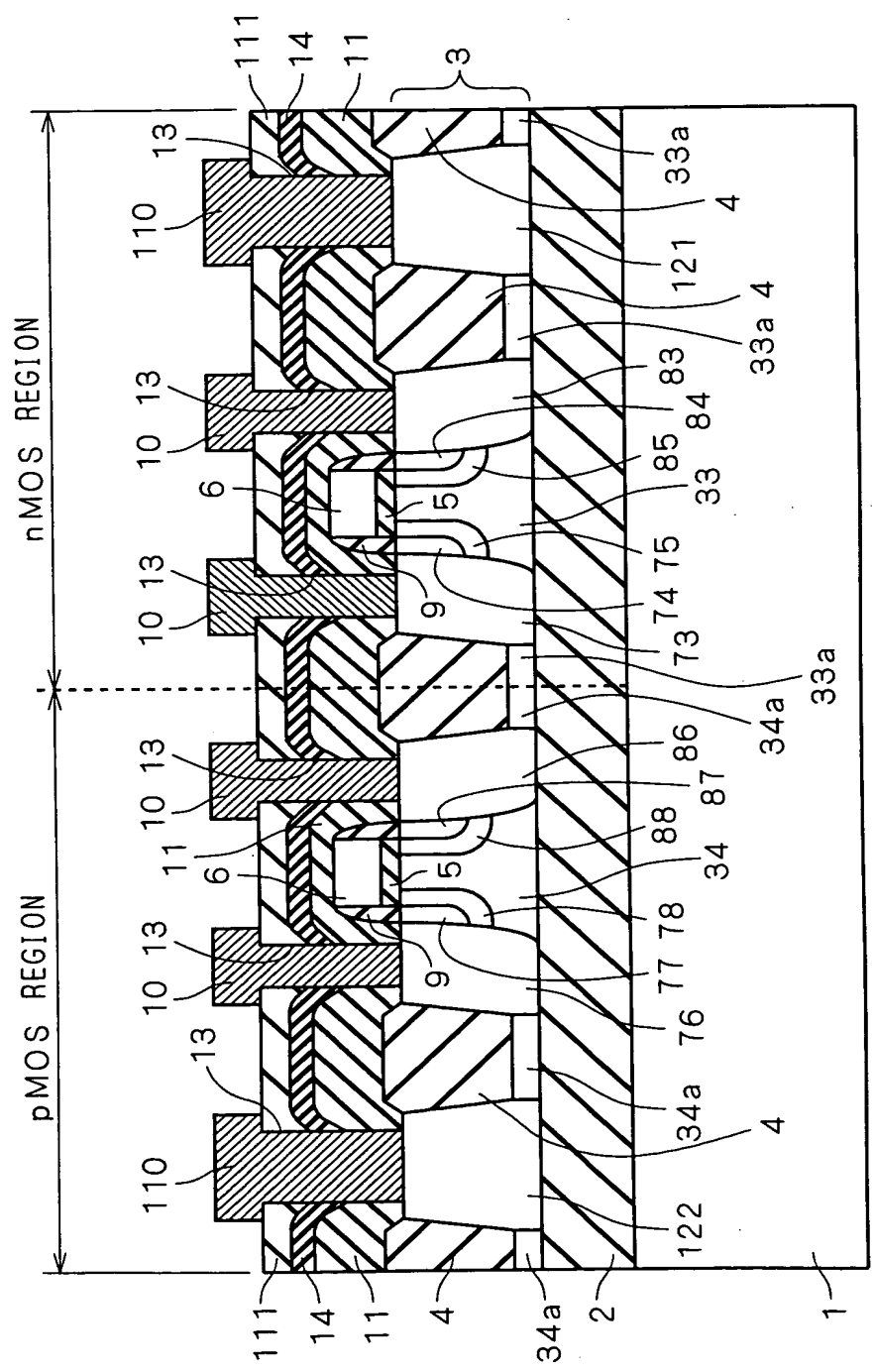


FIG. 14

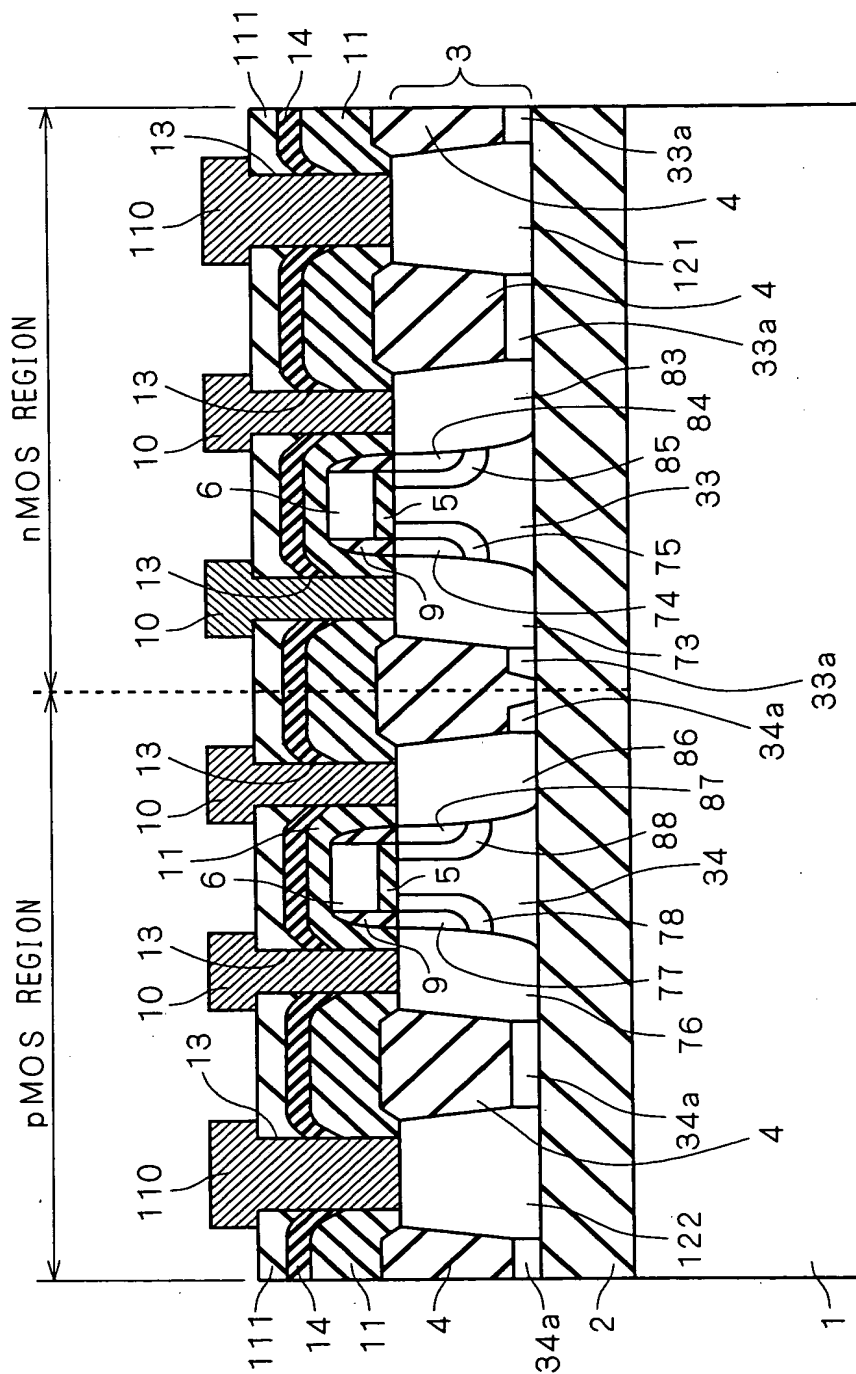


FIG. 15

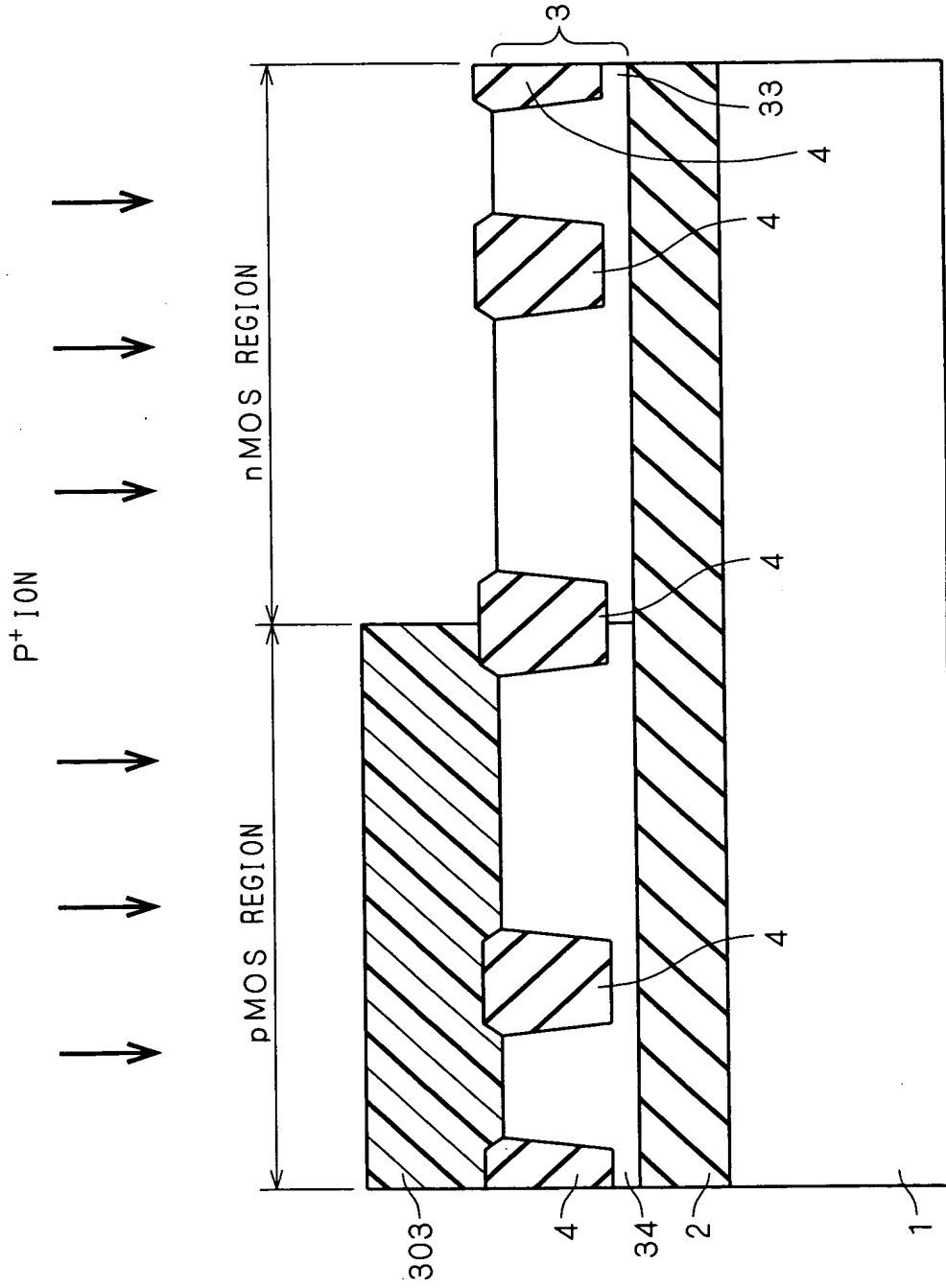


FIG. 16



FIG. 17

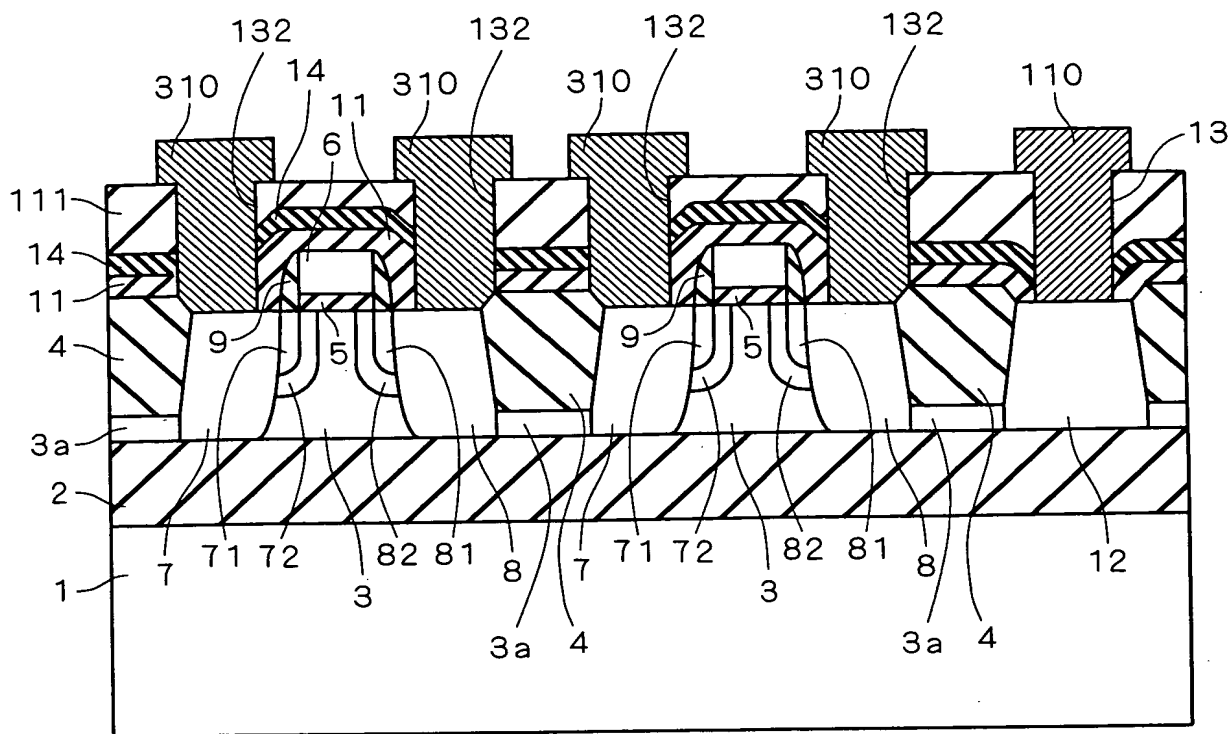
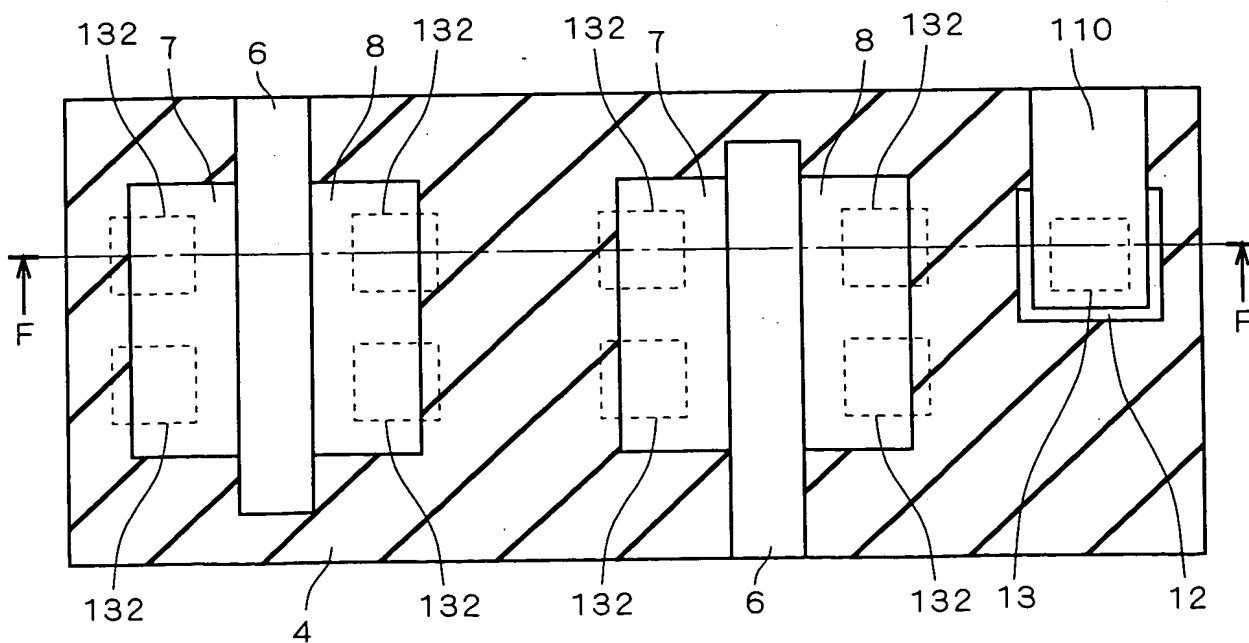


FIG. 18



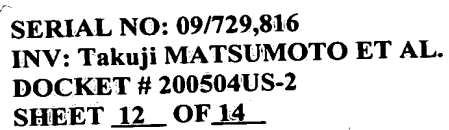
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FIG. 21

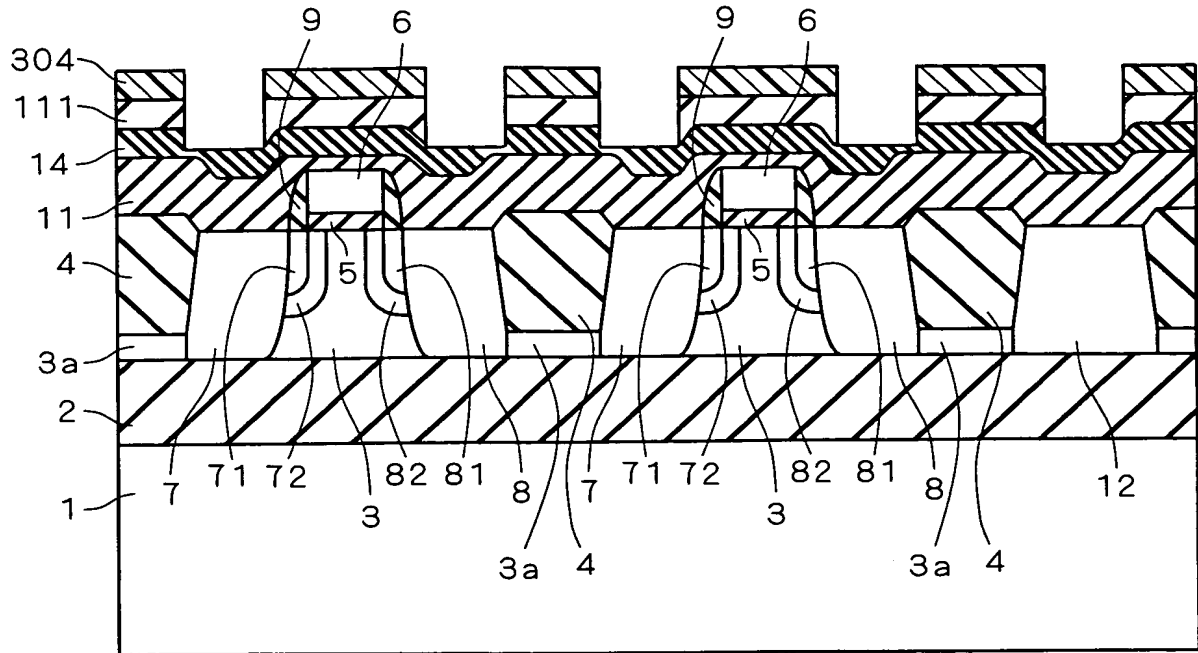


FIG. 22 BACKGROUND ART

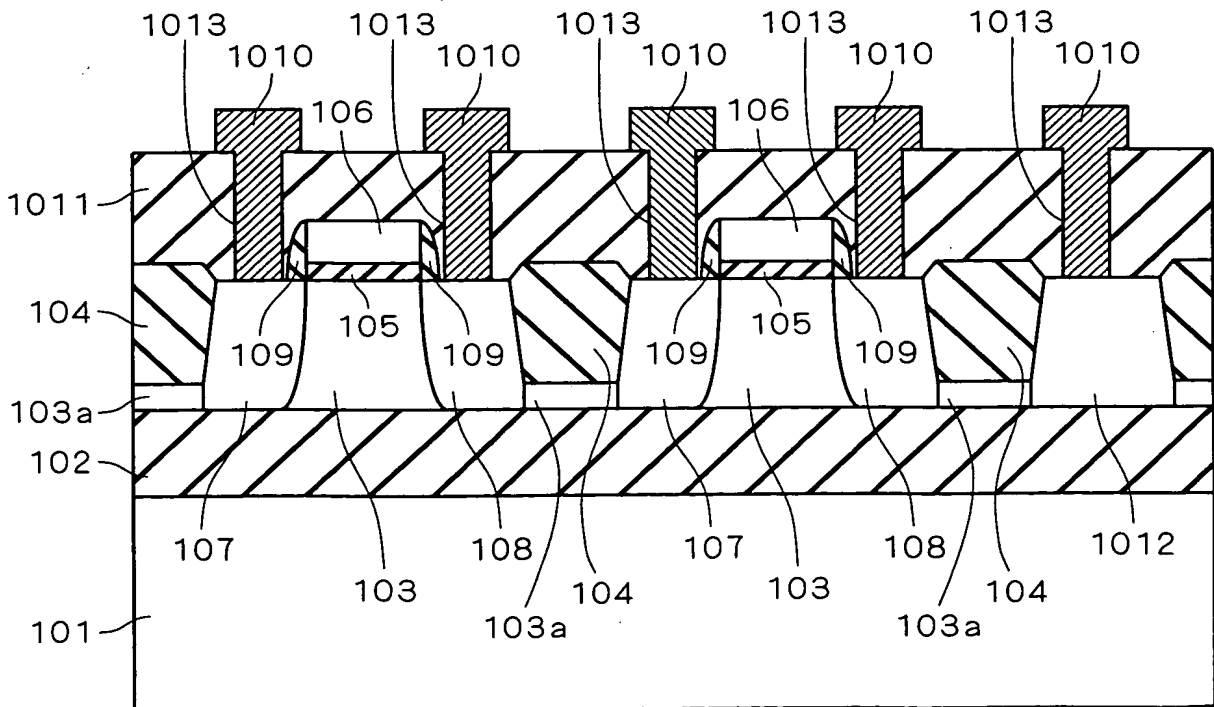


FIG. 24 BACKGROUND ART

